

**AMENDMENTS TO THE CLAIMS**

1. (Currently amended) A multilayer circuit component comprising a glass free ceramic substrate, a first glass-containing baked layer on the ceramic substrate and a second glass-containing baked layer on said first glass-containing layer, wherein the first glass-containing layer has a wettability relative to the ceramic substrate and the second glass-containing layer has a wettability relative to the first glass-containing layer such that the baking shrinkage rates of the first and second glass-containing layers are about the same.

2. (Original) A multilayer circuit component according to Claim 1, wherein a glass in the first glass-containing layer and a glass in the second glass-containing layer have softening temperatures which are different.

3. (Original) A multilayer circuit component according to Claim 2, wherein the glass of said first glass-containing layer has a contact angle relative to said substrate which is larger than the contact angle of the glass of said second glass-containing layer relative to said first glass-containing layer; and wherein the said glass of said first glass-containing layer has a softening temperature which is lower than the softening temperature of the glass of said second glass-containing layer.

4. (Original) A multilayer circuit component according to Claim 2, wherein the glass of said first glass-containing layer has a contact angle relative to said substrate which is smaller than the contact angle of the glass of said second glass-containing layer relative to said first glass-containing layer; and wherein the glass of said first glass-containing layer has a softening temperature which is higher than the softening temperature of the glass of said second glass-containing layer.

5. (Original) A multilayer circuit component according to Claim 2, wherein the difference between the softening temperatures of the glass of said first glass-containing layer and the glass of said second glass-containing layer is at least about 30°C.

6. (Previously amended) A multilayer circuit component according to Claim 1, wherein each of the first and second glass-containing layers comprise glass and ceramic, and the glass contents of the first and second glass-containing layers are different.

7. (Original) A multilayer circuit component according to Claim 6, wherein the glass of said first and second glass-containing layers are low softening temperature glasses.

8. (Original) A multilayer circuit component according to Claim 6, wherein the glass of the first glass-containing layer has a contact angle relative to said substrate which is larger than the contact angle of the glass of the second glass-containing layer relative to said first glass-containing layer; and wherein the glass content of said first glass-containing layer is larger than the glass content of said second glass-containing layer.

9. (Original) A multilayer circuit component according to Claim 6, wherein the glass of the first glass-containing layer has a contact angle relative to said substrate which is smaller than the contact angle of the glass constituting said second glass-containing layer relative to said first glass-containing layer; and wherein the glass

content of said first glass-containing layer is smaller than the glass content of said second glass-containing layer.

10. (Original) A multilayer circuit component according to Claim 6, wherein the glass of the first glass-containing layer has a contact angle relative to said substrate which is larger than the contact angle of the glass of said second glass-containing layer relative to said first glass-containing layer; and wherein the content of low softening temperature glass in the first glass-containing layer is larger than the content of low softening temperature glass in the second glass-containing layer.

11. (Original) A multilayer circuit component according to Claim 6, wherein the glass of first glass-containing layer has a contact angle relative to said substrate which is smaller than the contact angle of the glass of said second glass-containing layer relative to said first glass-containing layer; and the content of low softening temperature glass in the first glass-containing layer is smaller than the content of low softening temperature glass in the second glass-containing layer.

12. (Original) A multilayer circuit component according to Claim 6, wherein the glasses of the each of the first and second glass-containing layers comprise at least two different glasses of which at least one is a low softening temperature glass; and wherein the proportion of low softening temperature glass relative to total glass in said first and second glass-containing layers are different.

13. (Original) A multilayer circuit component according to Claim 12, wherein the glass of said first glass-containing layer has a contact angle relative to said substrate which is larger than the contact angle of the glass of said second glass-containing layer relative to said first glass-containing layer; and the content of glass in

said first glass-containing layer is larger than the content of glass in said second glass-containing layer.

14. (Original) A multilayer circuit component according to Claim 12, wherein the glass of the first glass-containing layer has a contact angle relative to said substrate which is smaller than the contact angle of the glass of the second glass-containing layer relative to said first glass-containing layer; and the content of glass in said first glass-containing layer is smaller than the content of glass in said second glass-containing layer.

15-24. (Cancelled).

25. (Previously presented) A multilayer circuit component according to claim 1, wherein the first and second glass-containing layers each comprise a photosensitive glass paste which has been exposed, developed and baked.

26. (New) A multilayer circuit component according to claim 25, wherein the circuit substrate comprises alumina.

27. (New) A multilayer circuit component according to claim 1, wherein the circuit substrate comprises alumina.